Title (en)

ACHIEVING ELECTROMAGNETIC INTERFERENCE SHIELDING PROTECTION BY DEPOSITION OF HIGHLY CONDUCTIVE COMPOSITIONS

Title (de)

SCHUTZ VOR ELEKTROMAGNETISCHER INTERFERENZ DURCH ABSCHEIDUNG VON HOCHLEITFÄHIGEN ZUSAMMENSETZUNGEN

Title (fr)

RÉALISATION D'UNE PROTECTION TELLE QU'UN BLINDAGE CONTRE LES INTERFÉRENCES ÉLECTROMAGNÉTIQUES PAR DÉPÔT DE COMPOSITIONS HAUTEMENT CONDUCTRICES

Publication

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Application

EP 16833605 A 20160729

Priority

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- US 2016044700 W 20160729

Abstract (en)

[origin: WO2017023747A1] Provided herein are highly conductive compositions (having a volume resistivity no greater than 1 x 10-3 Ohms.cm) using silver flake, powder or suspension in solvent for electromagnetic interference (EMI) applications. This high conductivity will allow the use of very thin films for EMI shielding protection, which in turn will be helpful to reduce package sizes. In some embodiments, the coating composition is applied on the device surface by suitable means, e.g., by an electrostatic spray process, air spray process, ultrasonic spray process, spin coating process, or the like.

IPC 8 full level

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CPC (source: EP KR US)

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